

MA3J7440G

Silicon epitaxial planar type

For super high speed switching

For small current rectification

■ Features

- High-density mounting is possible
- Forward current (Average) $I_{F(AV)} = 200$ mA rectification is possible

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	200	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

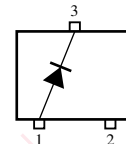
Note) *: $t = 1$ s

■ Package

- Code
SMini3-F2
- Pin Name
1: Anode
2: N.C.
3: Cathode

■ Marking Symbol: M1M

■ Internal Connection

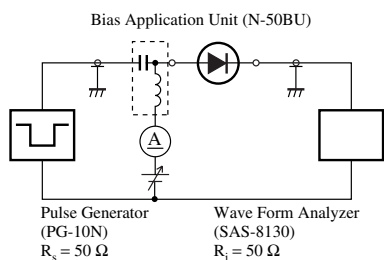
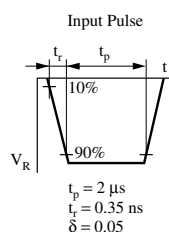
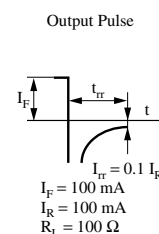


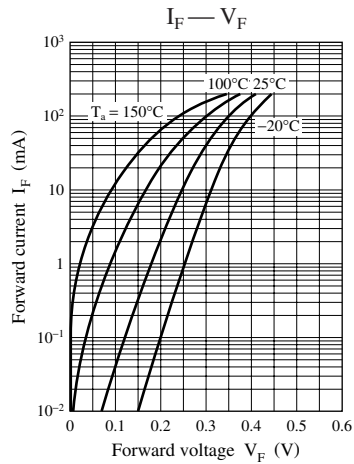
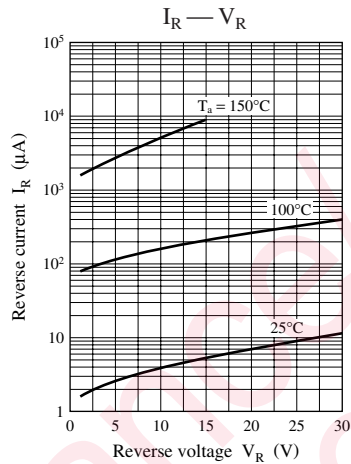
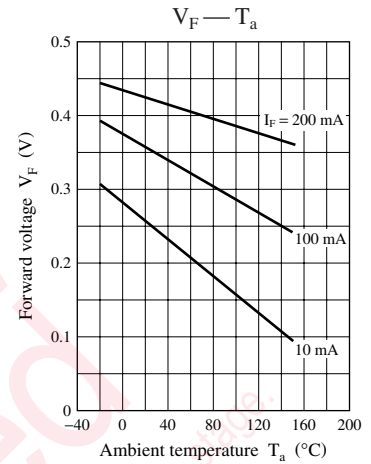
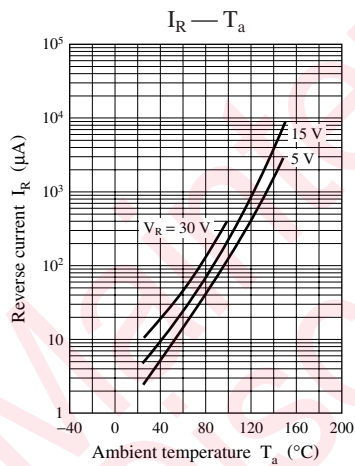
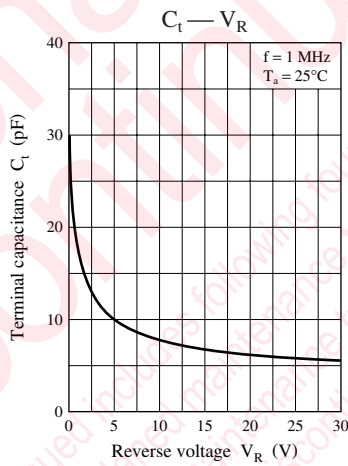
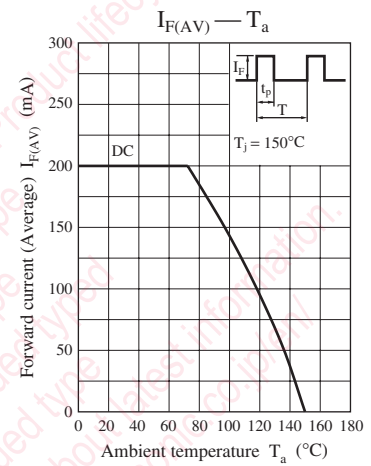
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200$ mA			0.55	V
Reverse current	I_R	$V_R = 30$ V			50	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$		3.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

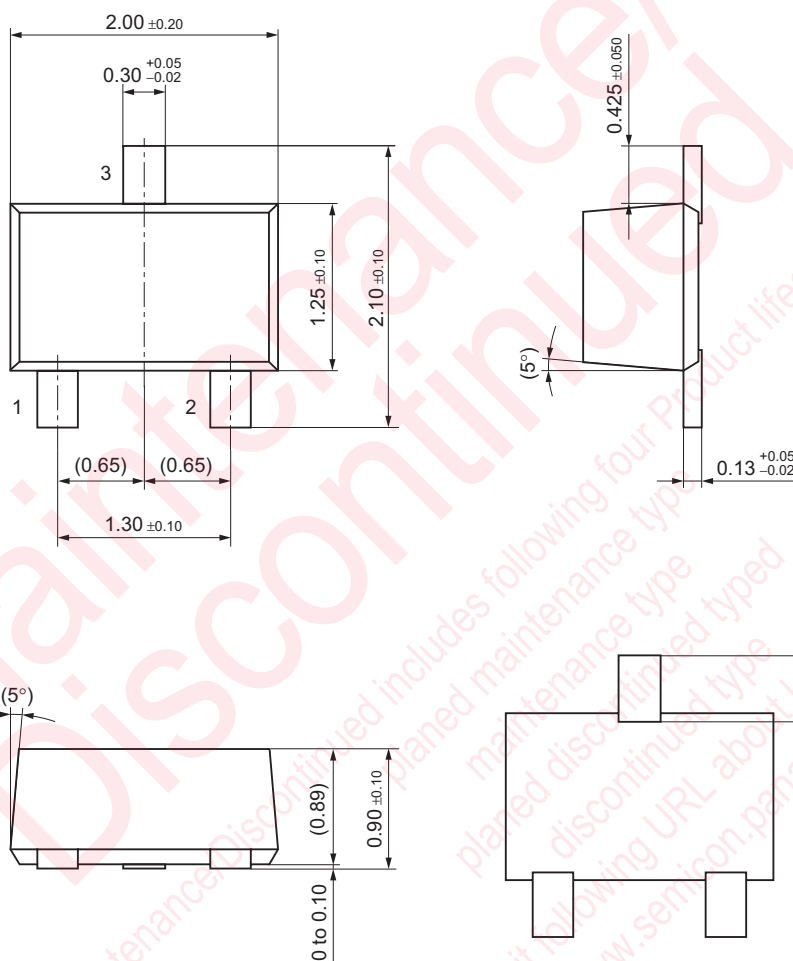
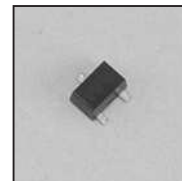
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz.
4. *: t_{rr} measurement circuit





SMini3-F2

Unit: mm



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